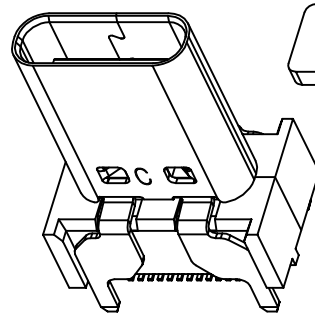
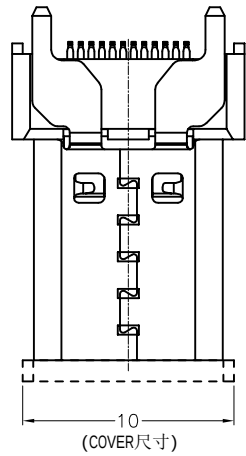
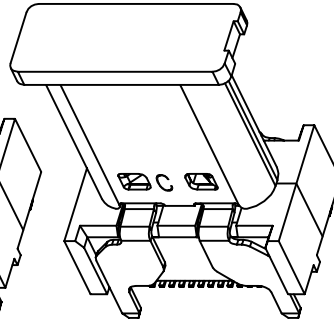


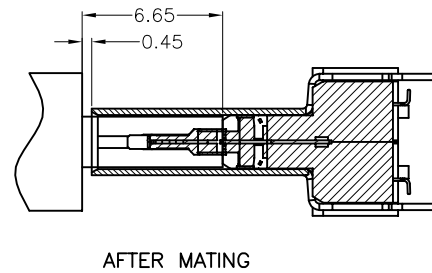
THE PART MEETS TECONN "GP001" COMPLIANCE NEW REV.



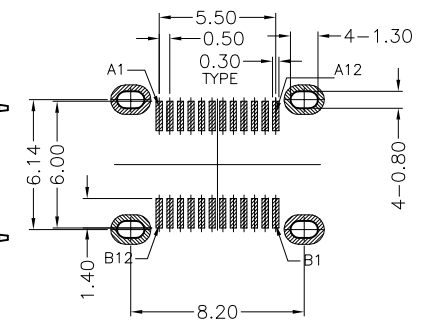
WITHOUT COVER



WITH COVER



AFTER MATING



RECOMMEND P.C.B LAYOUT (COMPONENT SIDE)

TOLERANCE FOR PCB LAYOUT IS ± 0.05

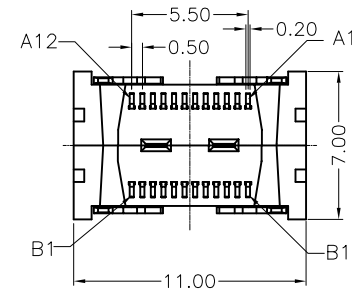
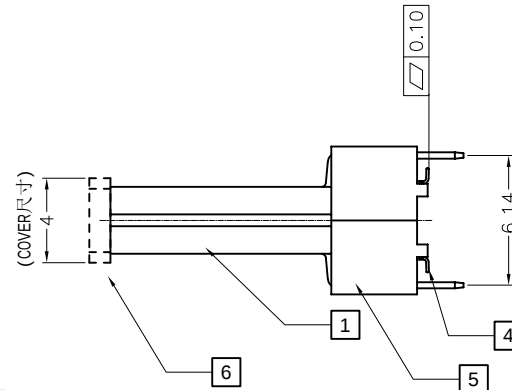
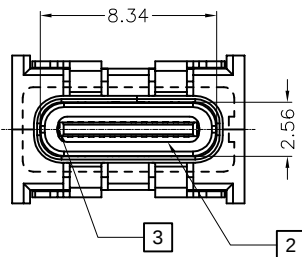
KEEP OUT AREA

A4Q2403-C-XX-R

Mating Area plating

- 01: Au 1u"Min.
- 03: Au 3u"Min.
- 05: Au 5u"Min.
- 10: Au 10u"Min.
- 15: Au 15u"Min.
- 30: Au 30u"Min.

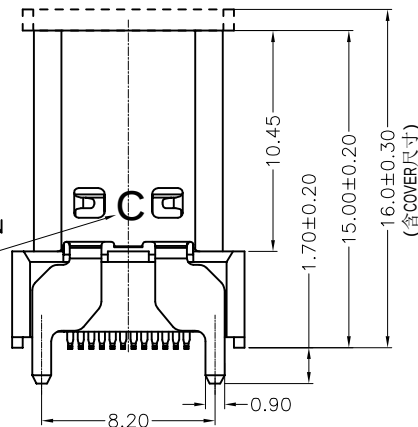
- 1. Contact Resistance: 40mOHM Max.;
- 2. Dielectric Withstanding Voltage: 100V AC For 1 Minute;
- 3. Insulation Resistance: 100M OHM Min.;
- 4. Mating And unmating Force:
Mating Force: 5~20N
Unmating Force: 8~20N;
6~20N AFTER TEST;
- 5. Durability: 10000 Cycles;



USB TYPE-C PIN ASSIGNMENTS

PIN NUMBER	SIGNAL NAME	PIN NUMBER	SIGNAL NAME
A1	GND	B12	GND
A2	TX1+	B11	RX1+
A3	TX1-	B10	RX1-
A4	Vbus	B9	Vbus
A5	CC1	B8	SBU2
A6	D+	B7	D-
A7	D-	B6	D+
A8	SBU1	B5	CC2
A9	Vbus	B4	Vbus
A10	RX2-	B3	TX2-
A11	RX2+	B2	TX2+
A12	GND	B1	GND

IDENTIFICATION MARK



REV	ECN NO	DESCRIPTION	DESIGN	DATE
B	TE2020-0264	Change Molding structure	Quan Lei	2020/11/17
A	TE2020-0152	New Drawing	Quan Lei	2020/03/30

Item	Title	Material	Dispose	Q'TY
1	Shell	Stainless Steel	Ni:30u" Min.	1PCS
2	GND Plate	Stainless Steel		2PCS
3	Mid Plate	Stainless Steel		1PCS
4	Contact	Copper Alloy	Mating Area: See P/N Solder Tails: Matt Tin	24PCS
5	InsertMolding	High Temperature Plastic	UL 94V-0 Black	1PCS
6	COVER	High Temperature Plastic	UL 94V-0 Black	1PCS

X. ± 0.35	APPD: Lebon Lee	TITLE: USB 3.1 TYPE C FEMALE VERTICAL H15.0mm SMT TYPE	
.X ± 0.25	CHKD: /	PART NO: A4Q2403-C-XX-R	
.XX ± 0.15	DR: Quan Lei	DWG NO: CUSTOMER DRAWING	
.XXX ± 0.10		C-A4Q2403-C-XX-R	
X" ± 2 "			
X" ± 1.5 "			
	UNITS: mm	SCALE: 3:1	SHEET: 10F1
			REV: B